

TPS63901 1.8V~5.5V、75nA I_Q 昇降圧コンバータ、入力電流制限および DVS 機能付き、WCSP パッケージ

1 特長

- 入力電圧範囲: 1.8V~5.5V
- 1.8V~5V の出力電圧範囲 (100mV ステップ)
 - 外付け抵抗によりプログラム可能
 - SEL ピンで 2 つのプリセット出力電圧を切り替え可能
- 出力電流: 400mA 超 ($V_I \geq 2.0V$, $V_O = 3.3V$)
 - スタック可能: 複数のデバイスを並列接続することでより大きな出力電流に対応
- 10 μ A の負荷電流で 90% を超える効率
 - 75nA の静止電流
 - 60nA のシャットダウン電流
- シングル・モード動作
 - 降圧、昇降圧、昇圧動作間のモード遷移が不要
 - 低い出力リップル
 - 非常に優れた過渡性能
- 堅牢な動作機能
 - ソフト・スタート内蔵
 - 8 つの設定値を持つプログラム可能な入力電流制限 (1mA~100mA および無制限)
 - 出力短絡および過熱保護
- 小さなソリューション・サイズ
 - 小型の 2.2 μ H インダクタ、1 つの 22 μ F 出力コンデンサ
 - 12 ボール、1.5mm × 1.15mm、0.35mm ピッチの WCSP パッケージ

2 アプリケーション

- スマート・ウォッチ
- スマート・トラッカー
- ウェアラブル電子機器
- 医療用センサ・パッチおよび患者モニター
- スマート・メータおよびセンサ・ノード
- 電子スマート・ロック
- 産業用 IoT (スマート・センサ) および NB-IoT

3 概要

TPS63901 デバイスは、静止電流が非常に小さい (代表値 75nA) 高効率の同期整流昇降圧コンバータです。このデバイスは、32 段階の出力電圧設定値 (1.8V~5V) をユーザーがプログラム可能です。

動的な電圧スケーリング機能により、アプリケーションは動作中に 2 つの出力電圧を切り替えることができます。たとえば、スタンバイ動作中に、より低いシステム電源電圧を使用して電力を節約できます。

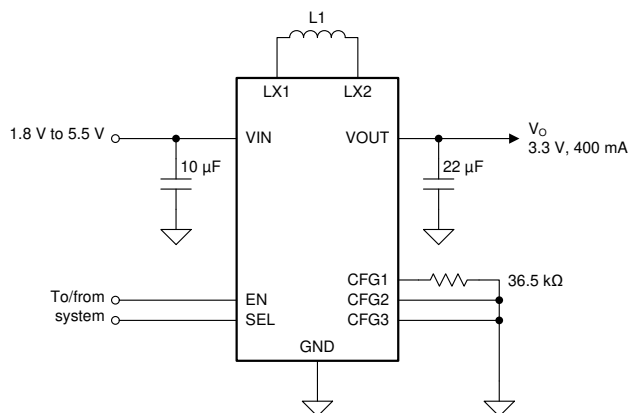
広い電源電圧範囲、プログラム可能な入力電流制限 (1mA~100mA および無制限) により、このデバイスは 3S アルカリ電池、1S Li-MnO₂、1S Li-SOCl₂ などの広範な 1 次電池と 2 次電池での使用に理想的です。

大きい出力電流能力により、一般的に使用される RF 規格 (たとえば、Sub-1GHz、BLE、LoRa、wM-Bus、NB-IoT) をサポートしています。

製品情報

型番 ⁽¹⁾	パッケージ	本体サイズ (公称)
TPS63901	WCSP (12)	1.50mm × 1.15mm

- (1) 利用可能なパッケージについては、このデータシートの末尾にある注文情報を参照してください。



概略回路図



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4 Pin Configuration and Functions

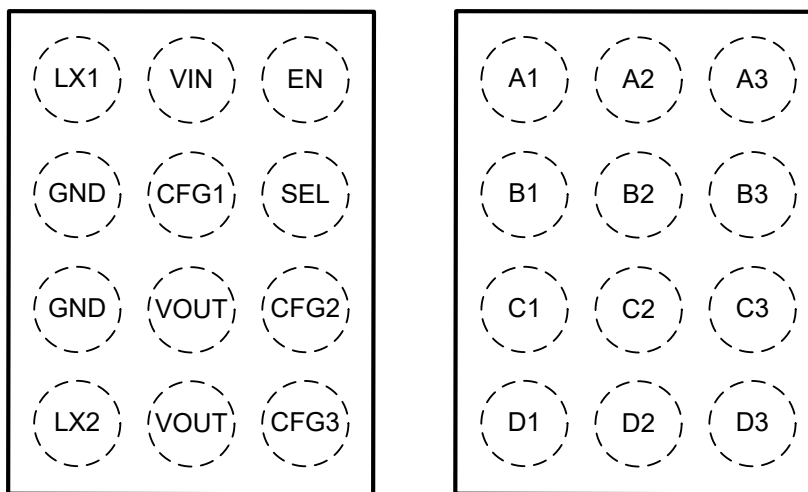


図 4-1. 12-Ball WCSP Package (Top View)

表 4-1. Pin Functions

Pin		Type	Description
Name	No.		
LX1	A1	—	Switching node of the buck stage
VIN	A2	—	Supply voltage
EN	A3	I	Device enable. A high level applied to this pin enables the device and a low level disables it. It must not be left open.
GND	B1,C1	—	Ground
CFG1	B2	I	Configuration pin 1. Connect a resistor between this pin and ground to set $V_{O(2)}$ and input current limit. Must not be left open.
SEL	B3	I	Output voltage select. Selects $V_{O(2)}$ when a high level is applied to this pin. Selects $V_{O(1)}$ when a low level is applied to this pin. It must not be left open.
VOUT	C2,D2	—	Output voltage. The C2 and D2 pins must be connected together.
CFG2	C3	I	Configuration pin 2. Connect a resistor between this pin and ground to set $V_{O(2)}$ and input current limit. Must not be left open.
LX2	D1	—	Switching node of the boost stage
CFG3	D3	I	Configuration pin 3. Connect a resistor between this pin and ground to set $V_{O(1)}$. Must not be left open.

5 Specifications

5.1 Absolute Maximum Ratings

over operating junction temperature range (unless otherwise noted) ⁽¹⁾

		MIN	MAX	UNIT
V_I	Input voltage (V_{IN} , LX1, LX2, VOUT, EN, CFG1, CFG2, CFG3, SEL) ⁽²⁾	−0.3	5.9	V
T_J	Operating junction temperature	−40	150	°C
T_{stg}	Storage temperature	−65	150	°C

- (1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) All voltage values are with respect to network ground terminal, unless otherwise noted.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±750	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_I	Supply voltage	1.8		5.5	V
V_O	Output voltage	1.8		5.0	V
C_I	Input capacitance ($V_I = 2.5$ V to 5 V, $V_O = 3.3$ V, $I_O = 0.4$ A) ⁽¹⁾	5			μF
C_O	Output capacitance ($V_I = 2.5$ V to 5 V, $V_O = 3.3$ V, $I_O = 0.4$ A) ⁽¹⁾	10			μF
$C_{(CFG)}$	Capacitance (CFG1, CFG2, CFG3)			10	pF
L	Inductance		2.2		μH
I_{SAT}	Inductor saturation current rating	Unlimited current setting	2		A
		≤ 100-mA current settings	1		
T_A	Operating ambient temperature	−40		85	°C
T_J	Operating junction temperature	−40		125	°C

- (1) Effective capacitance after DC bias effects have been considered.

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		YCJ (WCSP)	UNIT
		12 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	102.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	0.6	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	26.1	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.3	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	26.1	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

5.5 Electrical Characteristics

$T_J = -40^{\circ}\text{C}$ to 125°C , $V_I = 3.0\text{ V}$, $V_O = 2.5\text{ V}$. Typical values are at $T_J = 25^{\circ}\text{C}$ (unless otherwise noted).

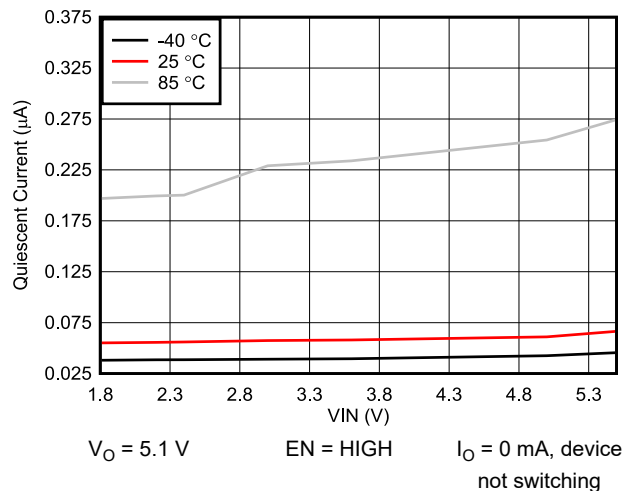
PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
SUPPLY							
I _Q	Quiescent current into VIN	V(EN) = 3 V, no load, not switching, "unlimited" current setting; T _J = −40°C to 85°C		0.075		1	μA
I _{SD}	Shutdown current into VIN	V(EN) = 0 V ; T _J = −40°C to 85°C		60			nA
V _{IT+(UVLO)}	Positive-going UVLO threshold voltage			1.73	1.75	1.77	V
V _{hys(UVLO)}	UVLO threshold voltage hysteresis			90	100	110	mV
V _{IT+(POR)}	Positive-going POR threshold voltage			1.37		1.74	V
I/O SIGNALS							
V _{IH}	High-level input voltage (EN, SEL)					1.2	V
V _{IL}	Low-level input voltage (EN, SEL)			0.4			V
	Input current (EN, SEL)	V _(EN) , V _(SEL) = 1.8 V or 0 V		±1		±10	nA
POWER SWITCH							
r _{DS(on)}	On-state resistance	Q1	V _I = 3 V, V _O = 5 V, test current = 1 A	140		mΩ	
		Q2	V _I = 3 V, V _O = 3 V, test current = 1 A	95			
		Q3	V _I = 3 V, V _O = 3 V, test current = 1 A	95			
		Q4	V _I = 5 V, V _O = 3 V, test current = 1 A	140			
CURRENT LIMIT							
	Peak current limit during start-up (Q1)	V _I = 3.6 V, unlimited current limit setting		0.35		0.83	A
	Peak current limit (Q1)	V _I = 1.8 V, V _O = 3.6 V, unlimited current limit setting		1.33	1.45	1.6	A
		V _I = 3.6 V, V _O = 3.3 V, 100-mA current limit setting		0.15	0.29	0.51	
	Average input current limit	T _J = −40°C to 85°C	1-mA setting	1		mA	
			2.5-mA setting	2.5			
			5-mA setting	5			
			10-mA setting	10			
			25-mA setting	25			
			50-mA setting	50			
			100-mA setting	100			
OUTPUT							
	Output voltage DC accuracy	I _O = 1 mA, C _{O(eff)} = 10 μF, L _(eff) = 2.2 μH				±1.5%	
CONTROL							
	Internal reference resistor			33			kΩ

5.5 Electrical Characteristics (続き)

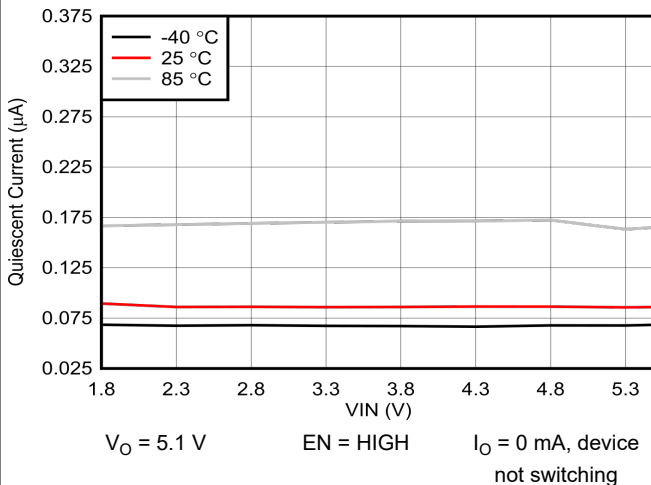
$T_J = -40^{\circ}\text{C}$ to 125°C , $V_I = 3.0\text{ V}$, $V_O = 2.5\text{ V}$. Typical values are at $T_J = 25^{\circ}\text{C}$ (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
R _{CFG}	R2D setting #0			0	0.1	kΩ
	R2D setting #1		−3%	0.511	+3%	
	R2D setting #2		−3%	1.15	+3%	
	R2D setting #3		−3%	1.87	+3%	
	R2D setting #4		−3%	2.74	+3%	
	R2D setting #5		−3%	3.83	+3%	
	R2D setting #6		−3%	5.11	+3%	
	R2D setting #7		−3%	6.49	+3%	
	R2D setting #8		−3%	8.25	+3%	
	R2D setting #9		−3%	10.5	+3%	
	R2D setting #10		−3%	13.3	+3%	
	R2D setting #11		−3%	16.2	+3%	
	R2D setting #12		−3%	20.5	+3%	
	R2D setting #13		−3%	24.9	+3%	
	R2D setting #14		−3%	30.1	+3%	
	R2D setting #15		−3%	36.5	+3%	
PROTECTION FEATURES						
	Thermal shutdown threshold temperature		140	150	160	°C
	Thermal shutdown hysteresis		15	20	25	°C
TIMING PARAMETERS						
t _d (POR)	POR signal delay after reaching POR threshold			3.8		ms
t _d (EN)	Delay between a rising edge on the EN pin and the start of the output voltage ramp	Supply voltage stable before EN pin goes high			1.5	ms
t _w (SS)	Soft-start step duration	V _O > 1.8 V	100	125	150	μs
t _d (SEL)	Delay between a change in the state of the SEL pin and the first step change in the output voltage			30	40	μs
t _w (DVS)	Dynamic voltage scaling step duration		100	125	150	μs
t _d (RESTART)	Restart delay after protection			10	11	ms

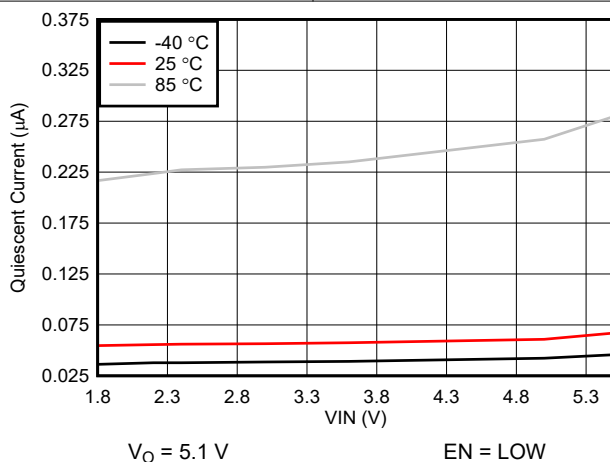
5.6 Typical Characteristics



5-1. Quiescent Current into VIN vs Input Voltage



5-2. Quiescent Current into VOUT vs Input Voltage



5-3. Shutdown Current vs Input Voltage

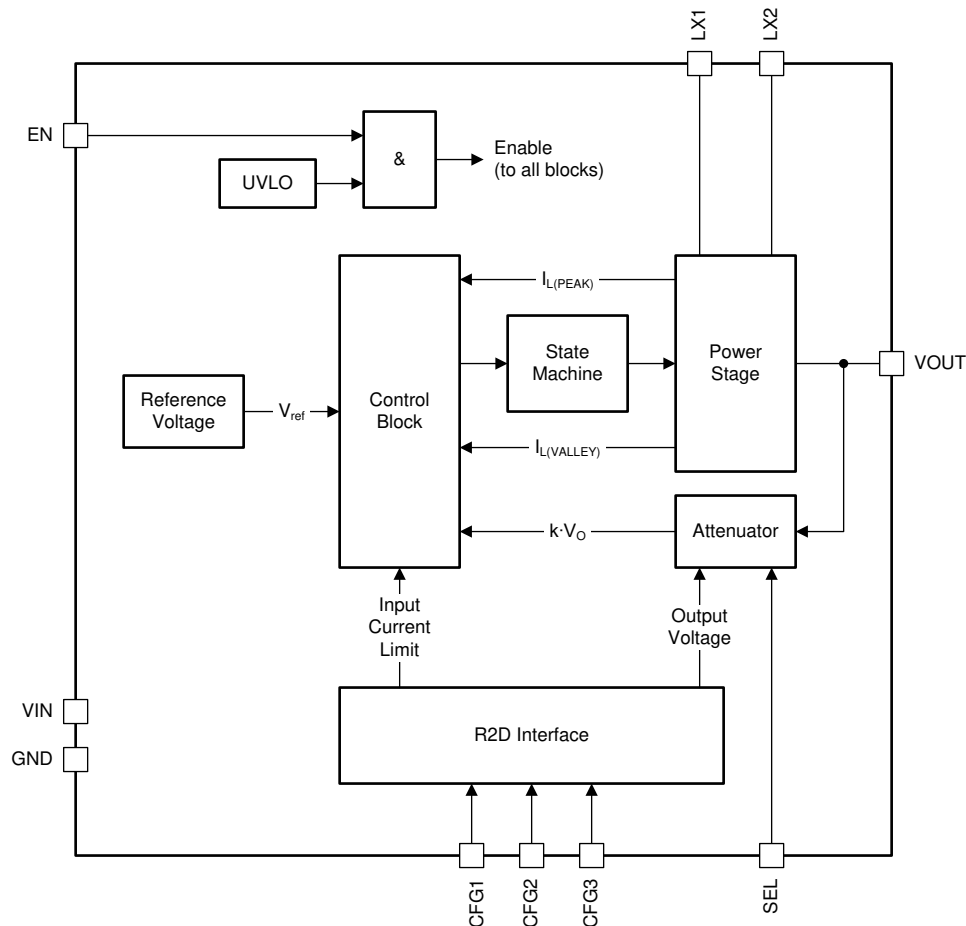
6 Detailed Description

6.1 Overview

The TPS63901 device is a four-switch synchronous buck-boost converter with a maximum output current of 400 mA. The device has a single-mode operation that allows the device to regulate the output voltage to a level above, below, or equal to the input voltage without displaying the mode-switching transients and unpredictable inductor current ripple from which many other buck-boost devices suffer.

The switching frequency of the TPS63901 device varies with the operating conditions: it is lowest when I_O is low and increases smoothly as I_O increases.

6.2 Functional Block Diagram



6.3 Feature Description

6.3.1 Trapezoidal Current Control

Figure 6-1 shows a simplified block diagram of the power stage of the device. Inductor current is sensed in series with Q1 (the peak current) and Q4 (the valley current).

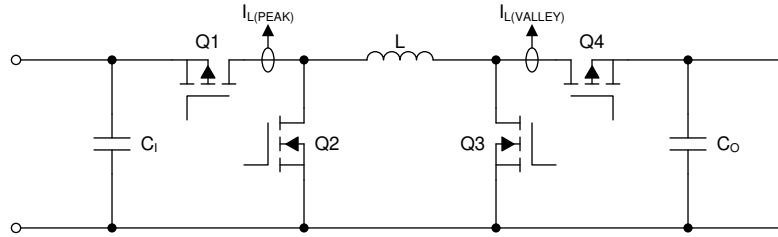


Figure 6-1. Power Stage Simplified Block Diagram

The device uses a trapezoidal inductor current to regulate its output under all operating conditions. Thus, the device only has one operating mode and does not display any of the mode-change transients or unpredictable switching displayed by many other buck-boost devices.

There are four phases of operation:

- Phase A – Q1 and Q3 are on and Q2 and Q4 are off.
- Phase B – Q1 and Q4 are on and Q2 and Q3 are off.
- Phase C – Q2 and Q4 are on and Q1 and Q3 are off.
- Phase D – Q2 and Q3 are on and Q1 and Q4 are off.

Figure 6-2 shows the inductor current waveform when $V_I > V_O$, Figure 6-3 shows the current waveform when $V_I = V_O$, and Figure 6-4 shows the current waveform when $V_I < V_O$.

Figure 6-2 through Figure 6-4 show the typical waveforms during continuous conduction mode (CCM) switching for three operating conditions. During discontinuous conduction mode (DCM), the typical inductor current waveforms look similar to CCM with Phase D at 0-A inductor current. In deep boost mode, where $V_I \ll V_O$, Phase C length gradually decreases to zero until the switching waveform becomes triangular.

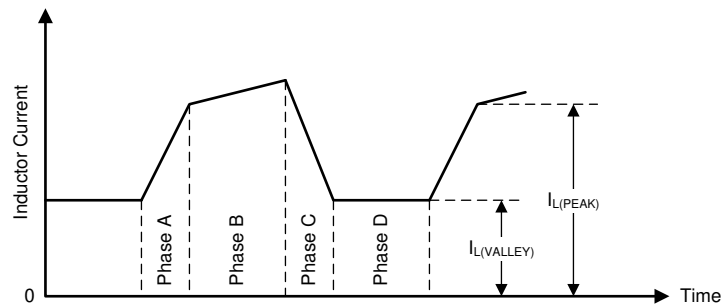


Figure 6-2. Inductor Current Waveform when $V_I > V_O$ (CCM)

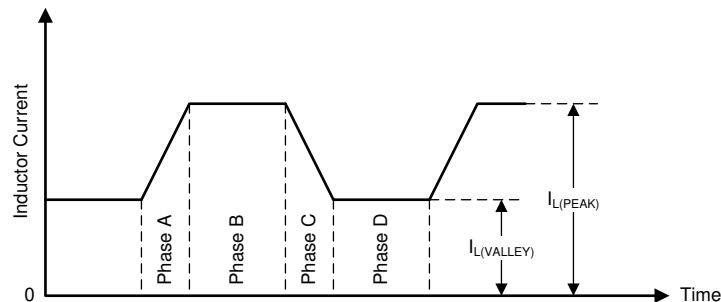


Figure 6-3. Inductor Current Waveform when $V_I = V_O$ (CCM)

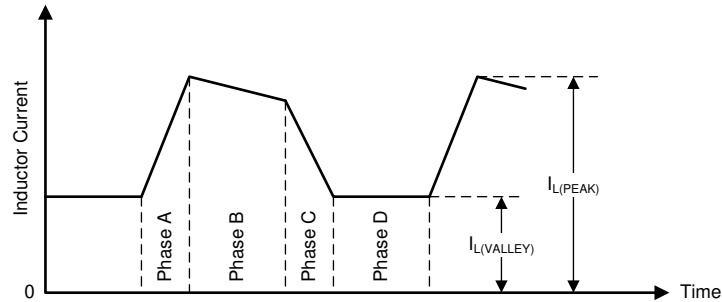


Figure 6-4. Inductor Current Waveform when $V_I < V_O$ (CCM)

The ideal relationship between V_I and V_O (that is, assuming no losses) is:

$$V_O = V_I \left(\frac{t_{w(A)} + t_{w(B)}}{t_{w(B)} + t_{w(C)}} \right) \quad (1)$$

where

- V_I is the input voltage.
- V_O is the output voltage.
- $t_{w(A)}$ is the duration of phase A.
- $t_{w(B)}$ is the duration of phase B.
- $t_{w(C)}$ is the duration of phase C.

By varying relative duration of each phase, the device can regulate V_O to be less than, equal to, or greater than V_I .

6.3.2 Device Enable and Disable

The device turns on when *all* of the following conditions are true:

- The supply voltage is greater than the positive-going undervoltage lockout (UVLO) threshold.
- The EN pin is high.

The device turns off when *at least one* of the following conditions is true:

- The supply voltage is less than the negative-going UVLO threshold.
- The EN pin is low.

Figure 6-13 shows a complete state diagram.

After the device turns on, the internal reference system starts, then the trimming information and the CFG pins are read out. The device ignores any further changes to the CFG pins during device operation.

Figure 6-5 shows the internal start-up sequence.

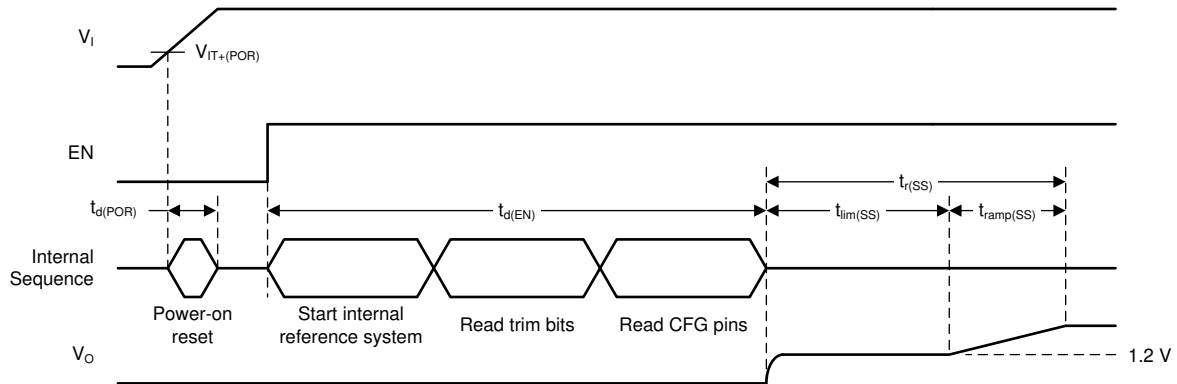


図 6-5. Internal Start-Up Sequence

6.3.3 Soft Start

The device has a soft-start feature that starts the device typically with 500-mA peak current limit until $V_O = 1.8\text{ V}$ and 500 μs elapsed when the input current limit is set to unlimited (see セクション 6.3.4). Afterward, the output voltage ramps in a series of discrete steps (see 図 6-6).

- When $V_O \leq 1.8\text{ V}$, peak current is limited to 500 mA typical for 500 μs .
- When $V_O > 1.8\text{ V}$, each step is 100 mV high and has a duration of 125 μs .

The total soft-start ramp-up time can be calculated with [Equation 2](#).

$$t_{r(SS)} = V_O \times 1.25 \left[\frac{\text{ms}}{\text{V}} \right] - 1.75 [\text{ms}] \quad (2)$$

where

- $t_{r(SS)}$ is the rise time of the output voltage in milliseconds.
- V_O is the output voltage in volts.

Figure 6-6 shows a typical start-up case.

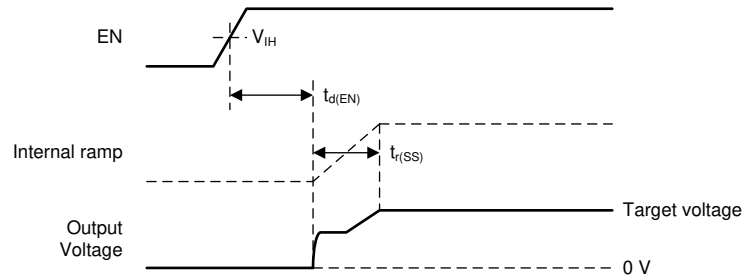


Figure 6-6. Start-Up Behavior

Figure 6-7 illustrates the start-up step size behavior.

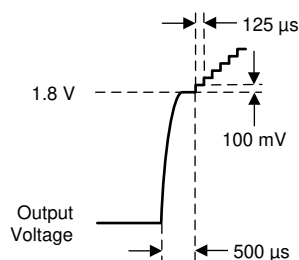


Figure 6-7. Typical Soft-Start Ramp Step Size

Table 6-1 shows the typical start-up time for a number of standard output voltages.

Table 6-1. Typical Start-Up Times

Output Voltage	Soft-Start Ramp-Up Time ($t_{r(SS)}$)	Start-Up Time ($t_{d(EN)} + t_{r(SS)}$)
1.8 V	0.5 ms	2 ms
2.5 V	1.375 ms	2.875 ms
3.3 V	2.375 ms	3.875 ms
5 V	4.5 ms	6 ms

If the output is prebiased – that is, the initial output voltage is not zero – the start-up behavior is as follows:

- If the prebias voltage is *lower* than the target voltage, the device does not start switching until the ramping output voltage is greater than the prebias voltage (see [Figure 6-8](#)).
- If the prebias voltage is *higher* than the target voltage, the device does not start to switch until the output voltage has decreased to the target voltage (see [Figure 6-9](#)). The device cannot actively discharge the output to the target voltage and relies on the load current to discharge the output capacitor and decrease the output voltage to the target value.

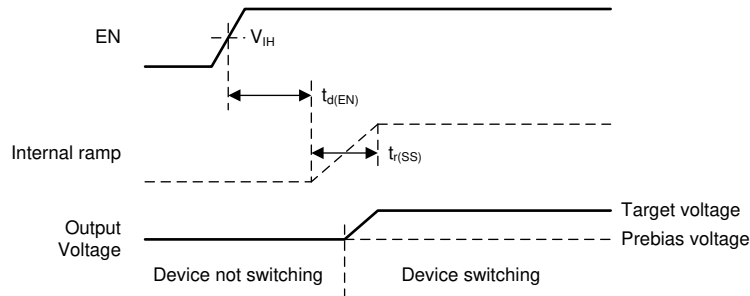


図 6-8. Start-Up Behavior into Prebiased (Low) Output

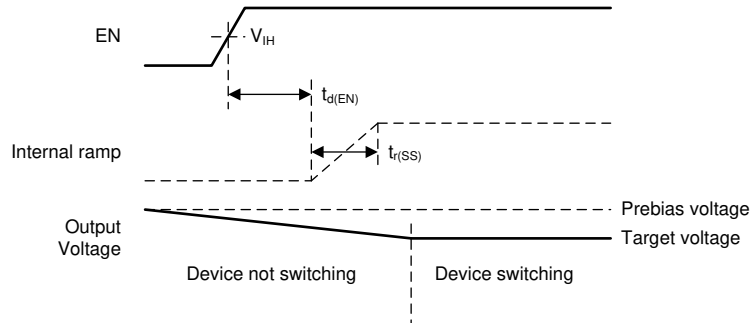


図 6-9. Start-Up Behavior into Prebiased (High) Output

6.3.4 Input Current Limit

The device can limit the current drawn from its supply, so that it can be used with batteries that do not support high peak currents. The input current limit is active during normal operation and at start-up to avoid high inrush current. The device has eight current limit settings:

- 1 mA
- 2.5 mA
- 5 mA
- 10 mA
- 25 mA
- 50 mA
- 100 mA
- Unlimited

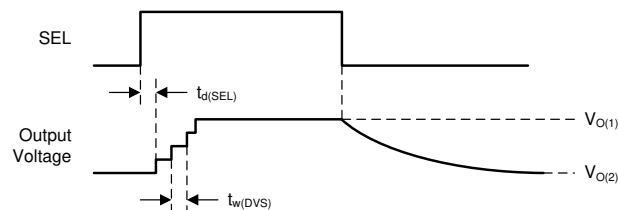
CFG1 and CFG2 pins select which setting is active (see [セクション 6.3.6](#)).

6.3.5 Dynamic Voltage Scaling

The device has a dynamic voltage scaling function to switch between the two output voltage settings. When the SEL pin changes state, the output voltage ramps to the new value in 100-mV steps. The duration of each step is 125 μs (see [図 6-10](#)).

The device does not actively discharge the output capacitor when the output voltage ramps to a lower level. This leads to a longer output voltage settling time when light load is applied (see [図 6-11](#)). The settling time can be calculated with [Equation 3](#).

$$t_{\text{settle}} = C_O \times \frac{V_{O(\text{HIGH})} - V_{O(\text{LOW})}}{I_O} \quad (3)$$


図 6-10. Dynamic Voltage Scaling with High Load

図 6-11. Dynamic Voltage Scaling with Light Load

6.3.6 Device Configuration (Resistor-to-Digital Interface)

The device has three configuration pins (CFG1, CFG2, and CFG3) that control its operation. When the device starts up, a resistor-to-digital (R2D) interface reads the values of the configuration resistors on the CFG pins and transfers the setting to an internal configuration register (see 図 6-12).

- CFG1 and CFG2 set $V_{O(2)}$ level and the input current limit.
- CFG3 sets $V_{O(1)}$ level.

To reduce power consumption, the device reads the value of the resistors connected to the configuration pins during start-up and then disables these pins. Once the device has started to operate, changes to the configuration pins have no effect.

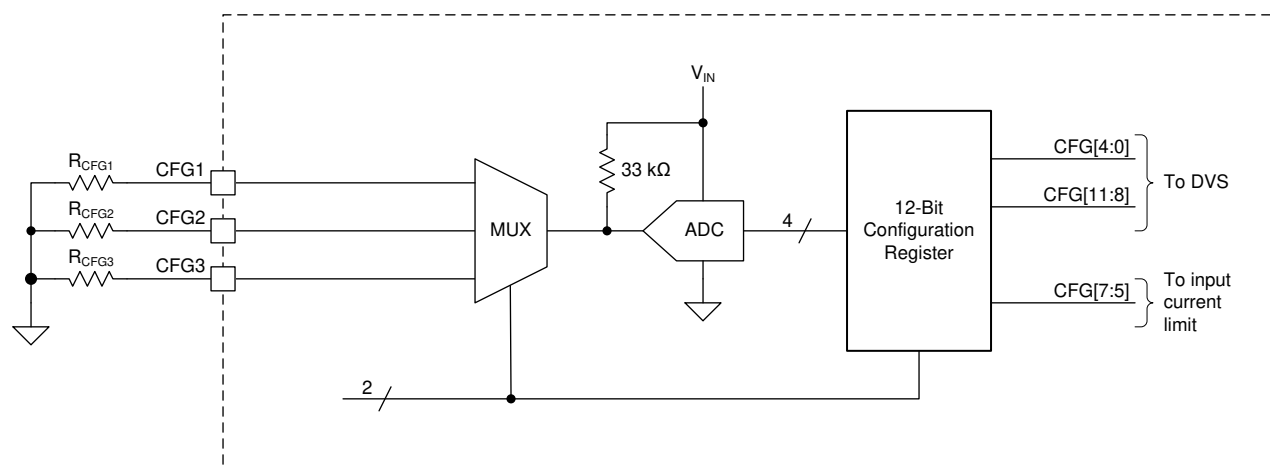

図 6-12. Resistor-to-Digital Interface Block Diagram

表 6-2 summarizes the resistor values needed to configure the device for different input current limit and output voltage (SEL = high) settings. For correct operation, use resistors with a tolerance of $\pm 1\%$ or better and a temperature coefficient of ± 200 ppm or better.

注

For correct operation, TI recommends that the total RMS error of the configuration resistors – including initial tolerance, temperature drift, and aging – is less than $\pm 3\%$.

表 6-2. Input Current Limit and Output Voltage (SEL = High) Settings

Output Voltage – V _{O(2)} (SEL = HIGH)		Input Current Limit							
		UNLIMITED	100 mA	50 mA	25 mA	10 mA	5 mA	2.5 mA	1 mA
1.8 V	R _{CFG1}	0 Ω							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
1.9 V	R _{CFG1}	511 Ω							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ

表 6-2. Input Current Limit and Output Voltage (SEL = High) Settings (続き)

Output Voltage – $V_{O(2)}$ (SEL = HIGH)		Input Current Limit							
		UNLIMITED	100 mA	50 mA	25 mA	10 mA	5 mA	2.5 mA	1 mA
2.0 V	R _{CFG1}	1.15 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
2.1 V	R _{CFG1}	1.87 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
2.2 V	R _{CFG1}	2.74 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
2.3 V	R _{CFG1}	3.83 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
2.4 V	R _{CFG1}	5.11 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
2.5 V	R _{CFG1}	6.49 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
2.6 V	R _{CFG1}	8.25 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
2.7 V	R _{CFG1}	10.5 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
2.8 V	R _{CFG1}	13.3 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
2.9 V	R _{CFG1}	16.2 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
3.0 V	R _{CFG1}	20.5 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
3.1 V	R _{CFG1}	24.9 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
3.2 V	R _{CFG1}	30.1 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
3.3 V	R _{CFG1}	36.5 kΩ							
	R _{CFG2}	0 Ω	511 Ω	1.15 kΩ	1.87 kΩ	2.74 kΩ	3.83 kΩ	5.11 kΩ	6.49 kΩ
3.4 V	R _{CFG1}	0 Ω							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
3.5 V	R _{CFG1}	511 Ω							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
3.6 V	R _{CFG1}	1.15 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
3.7 V	R _{CFG1}	1.87 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
3.8 V	R _{CFG1}	2.74 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
3.9 V	R _{CFG1}	3.83 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
4.0 V	R _{CFG1}	5.11 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
4.1 V	R _{CFG1}	6.49 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ

表 6-2. Input Current Limit and Output Voltage (SEL = High) Settings (続き)

Output Voltage – $V_{O(2)}$ (SEL = HIGH)		Input Current Limit							
		UNLIMITED	100 mA	50 mA	25 mA	10 mA	5 mA	2.5 mA	1 mA
4.2 V	R _{CFG1}	8.25 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
4.3 V	R _{CFG1}	10.5 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
4.4 V	R _{CFG1}	13.3 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
4.5 V	R _{CFG1}	16.2 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
4.6 V	R _{CFG1}	20.5 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
4.7 V	R _{CFG1}	24.9 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
4.8 V	R _{CFG1}	30.1 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ
5.0 V	R _{CFG1}	36.5 kΩ							
	R _{CFG2}	8.25 kΩ	10.5 kΩ	13.3 kΩ	16.2 kΩ	20.5 kΩ	24.9 kΩ	30.1 kΩ	36.5 kΩ

表 6-3 summarizes the resistor values needed to configure the device for different output voltage (SEL = low) settings. For correct operation, use resistors with a tolerance of $\pm 1\%$ or better and a temperature coefficient of better than ± 200 ppm.

表 6-3. Output Voltage (SEL Pin = Low) Settings

Output Voltage – $V_{O(1)}$ (SEL = LOW)	R _{CFG3}
1.8 V	0 Ω
2.0 V	511 Ω
2.1 V	1.15 kΩ
2.2 V	1.87 kΩ
2.3 V	2.74 kΩ
2.4 V	3.83 kΩ
2.5 V	5.11 kΩ
2.6 V	6.49 kΩ
2.7 V	8.25 kΩ
2.8 V	10.5 kΩ
3.0 V	13.3 kΩ
3.3 V	16.2 kΩ
3.6 V	20.5 kΩ
4.0 V	24.9 kΩ
4.5 V	30.1 kΩ
5.0 V	36.5 kΩ

6.3.7 SEL Pin

The SEL pin selects which configuration bits control the output voltage.

- When SEL = high, the output voltage $V_{O(2)}$ is set.

- When SEL = low, the output voltage $V_{O(1)}$ is set.

6.3.8 Short-Circuit Protection

6.3.8.1 Current Limit Setting = 'Unlimited'

The device has a built-in short circuit protection function to limit the current through Q1. The maximum current that flows is limited by the peak current limit. The output voltage decreases if the load is higher than the peak current limit. If the output voltage falls below 1.25 typically, the short circuit protection is activated. With short circuit protection activated, the input current is limited to 26 mA on average.

The device automatically restarts to normal operation after the short condition is removed.

6.3.8.2 Current Limit Setting = 1 mA to 100 mA

The input current limiting function automatically limits current during a short-circuit condition. The device regulates the average input current for as long as the short-circuit condition exists. If the output voltage falls below 1.25 V typically, the short circuit protection is activated. For input current limit settings of 100 mA, 50 mA, and 25 mA, the short circuit protection limits the input current to 26 mA on average. For input current limit setting of 10 mA, 5 mA, 2.5 mA, and 1 mA, the short circuit protection limits the input current to slightly above the typical values for each setting. 表 6-4 shows the typical short circuit currents for each input current limit setting.

The device automatically restarts to previous operation after the short condition is removed.

表 6-4. Typical Input Current During Short Circuit Condition ($V_O < 1.25$ V Typically) for All Input Current Limit Settings

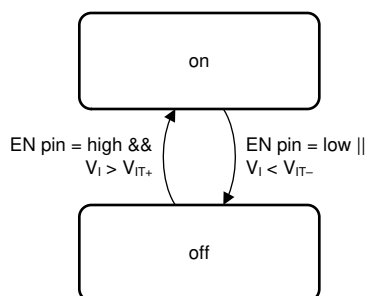
Input Current Limit Setting	Typical Short Circuit Input Current
1 mA	1.2 mA
2.5 mA	2.8 mA
5 mA	5.2 mA
10 mA	12 mA
25 mA	26 mA
50 mA	26 mA
100 mA	26 mA
Unlimited	26 mA

6.3.9 Thermal Shutdown

The device has a thermal shutdown function that disables the device if it gets too hot for correct operation. When the device cools down, it automatically restarts operation after a typical delay of $t_{d(RESTART)} = 10$ ms. The device starts with the soft-start feature (see [セクション 6.3.3](#)) and keeps the previously read CFG pin setting.

6.4 Device Functional Modes

The device has two functional modes: on and off. The device enters on mode when the voltage on the VIN pin is higher than the UVLO threshold and a high logic level is applied to the EN pin. The device enters off mode when the voltage on the VIN pin is lower than the UVLO threshold or a low logic level is applied to the EN pin.

**図 6-13. Device Functional Modes**

7 Application and Implementation

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

7.1 Application Information

The TPS63901 is a high-efficiency, non-inverting buck-boost converter with an extremely low quiescent current, suitable for applications that need a regulated output voltage from an input supply that can be higher or lower than the output voltage. The input current limit and output voltage are set through resistors connected to the three CFGx pins.

7.2 Typical Application

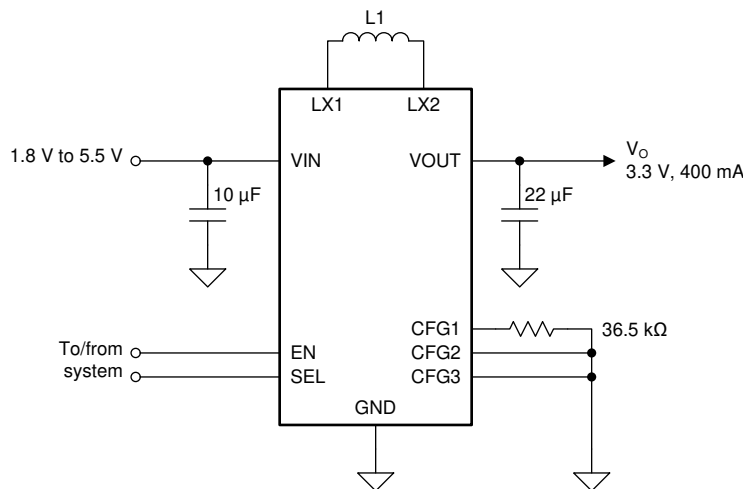


図 7-1. 3.3-V_{OUT} Typical Application

7.2.1 Design Requirements

The design guideline provides a component selection to operate the device within the [Recommended Operating Conditions](#).

表 7-1. Matrix of Output Capacitor and Inductor Combinations

Nominal Inductor Value [µH] ⁽¹⁾	Nominal Output Capacitor Value [µF] ⁽²⁾				
	10	22	47	100	≥ 300
2.2	+(3)	+(4)	+	+	+(5)

- (1) Inductor tolerance and current derating is anticipated. The effective inductance can vary by 20% and –30%.
 (2) Capacitance tolerance and DC bias voltage derating is anticipated. The effective capacitance can vary by 20% and –50%.
 (3) Output voltage ripple increases versus typical application.
 (4) Typical application. Other check marks indicate possible filter combinations.
 (5) Start-up time increased

7.2.2 Detailed Design Procedure

The first step is the selection of the output filter components. To simplify this process, the [Recommended Operating Conditions](#) outlines minimum and maximum values for inductance and capacitance. Tolerance and derating must be taken into account when selecting nominal inductance and capacitance.

7.2.2.1 Inductor Selection

The inductor selection is affected by several parameters such as inductor ripple current, output voltage ripple, transition point into power save mode, and efficiency. See 表 7-2 for typical inductors.

For high efficiencies, the inductor must have a low DC resistance to minimize conduction losses. Especially at high-switching frequencies, the core material has a high impact on efficiency. When using small chip inductors, the efficiency is reduced mainly due to higher inductor core losses, which needs to be considered when selecting the appropriate inductor. The inductor value determines the inductor ripple current. The larger the inductor value, the smaller the inductor ripple current and the lower the core and conduction losses of the converter. Conversely, larger inductor values cause a slower load transient response. To avoid saturation of the inductor, the peak current for the inductor in steady state operation is calculated using 式 5. Only the equation that defines the switch current in boost mode is shown because this provides the highest value of current and represents the critical current value for selecting the right inductor.

$$\text{Duty Cycle Boost} \quad D = \frac{V_{\text{OUT}} - V_{\text{IN}}}{V_{\text{OUT}}} \quad (4)$$

$$I_{\text{PEAK}} = \frac{I_{\text{out}}}{\eta \times (1 - D)} + \frac{V_{\text{in}} \times D}{2 \times f \times L} \quad (5)$$

where

- D is duty cycle in boost mode.
- f is the converter switching frequency.
- L is the inductor value.
- η is the estimated converter efficiency (use the number from the efficiency curves or 0.9 as an assumption).

注

The calculation must be done for the minimum input voltage in boost mode.

Calculating the maximum inductor current using the actual operating conditions gives the minimum saturation current of the inductor needed. TI recommends choosing an inductor with a saturation current 20% higher than the value calculated using 式 5. Possible inductors are listed in 表 7-2.

表 7-2. List of Recommended Inductors

Inductor Value [μH] ⁽¹⁾	Saturation Current [A]	DCR [mΩ]	Part Number	Manufacturer	Size (L × W × H mm)
2.2	3.5	21	XFL4020-222ME	Coilcraft	4 × 4 × 2
2.2	1.7	72	SRN3015TA-2R2M	Bourns	3 × 3 × 1.5
2.2	3.3	82	DFE252012F-2R2M	Murata	2.5 × 2 × 1.2
2.2	2.4	116	DFE201612E-2R2M	Murata	2.0 × 1.6 × 1.2
2.2	2.0	190	DFE201210U-2R2M	Murata	2.0 × 1.2 × 1.0

(1) See the [Third-party Products Disclaimer](#).

7.2.2.2 Output Capacitor Selection

For the output capacitor, use of small ceramic capacitors placed as close as possible to the VOUT and GND pins of the IC is recommended. The recommended nominal output capacitor value is a single 22 μF. If, for any reason, the application requires the use of large capacitors, which cannot be placed close to the IC, use a smaller ceramic capacitor in parallel to the large capacitor. The small capacitor must be placed as close as possible to the VOUT and GND pins of the IC.

It is important that the effective capacitance is given according to the recommended value in the *Recommended Operating Conditions*. In general, consider DC bias effects resulting in less effective capacitance. The choice of

the output capacitance is mainly a trade-off between size and transient behavior as higher capacitance reduces transient response overshoot and undershoot and increases transient response time. Possible output capacitors are listed in 表 7-3.

There is no upper limit for the output capacitance value.

At light load currents, the output voltage ripple is dependent on the output capacitor value. Larger output capacitors reduce the output voltage ripple. The leakage current of the output capacitor adds to the overall quiescent current.

表 7-3. List of Recommended Capacitors

Capacitor Value [μF] ⁽¹⁾	Voltage Rating [V]	Part Number	Manufacturer	Size (Metric)
22	6.3	GRM187R60J226ME15	Murata	0603 (1608)
22	6.3	GRM219R60J476ME44	Murata	0805 (3210)
47	6.3	GRM188R60J476ME15	Murata	0603 (1608)

(1) See the [Third-party Products Disclaimer](#).

7.2.2.3 Input Capacitor Selection

A 10-μF input capacitor is recommended to improve line transient behavior of the regulator and EMI behavior of the total power supply circuit. An X5R or X7R ceramic capacitor placed as close as possible to the VIN and GND pins of the IC is recommended. This capacitance can be increased without limit. If the input supply is located more than a few inches from the TPS63901 converter, additional bulk capacitance can be required in addition to the ceramic bypass capacitors. An electrolytic or tantalum capacitor with a value of 47 μF is a typical choice.

When operating from a high impedance source, a larger input buffer capacitor is recommended to avoid voltage drops during start-up and load transients.

The input capacitor can be increased without any limit for better input voltage filtering. The leakage current of the input capacitor adds to the overall quiescent current.

表 7-4. List of Recommended Capacitors

Capacitor Value [μF] ⁽¹⁾	Voltage Rating [V]	Part Number	Manufacturer	Size (Metric)
10	6.3	GRM188R60J106ME47	Murata	0603 (1608)
10	10	GRM188R61A106ME69	Murata	0603 (1608)
22	6.3	GRM187R60J226ME15	Murata	0603 (1608)

(1) See the [Third-party Products Disclaimer](#).

7.2.2.4 Setting The Output Voltage

The output voltage is set with the CFGx pins (see セクション 6.3.6).

7.2.3 Application Curves

表 7-5. Components for Application Characteristic Curves for V_{OUT} = 3.3 V

Reference ⁽¹⁾	Description ⁽²⁾	Part Number	Manufacturer
U1	400-mA ultra low I _Q buck-boost converter (1.5 mm × 1.15 mm)	TPS63901YCJ	Texas Instruments
L1	2.2 μH, 2.5 mm × 2 mm 3.3 A, 82 mΩ	DFE252012F-2R2M	Murata
C1	10 μF, 0603, ceramic capacitor, ±20%, 6.3 V	GRM188R60J106ME47	Murata
C2	22 μF, 0603, ceramic capacitor, ±20%, 6.3 V	GRM187R60J226ME15	Murata
CFG1	36.5 kΩ, 0603 resistor, 1%, 100 mW	Standard	Standard
CFG2	0 Ω, 0603 resistor, 1%, 100 mW	Standard	Standard
CFG3	0 Ω, 0603 resistor, 1%, 100 mW	Standard	Standard

(1) See the [Third-Party Products Disclimer](#)

- (2) For other output voltages, refer to [表 7-1](#) for resistor values.

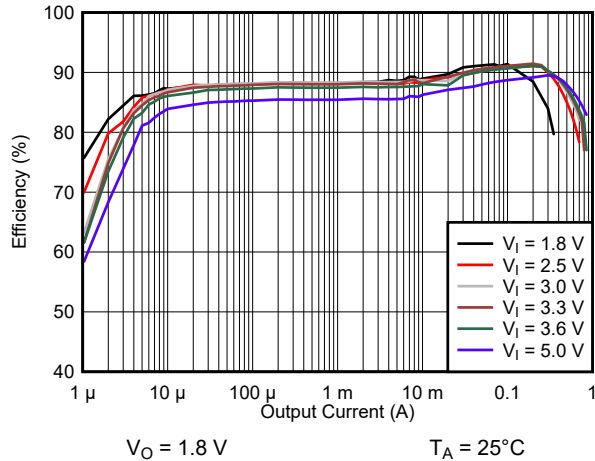


Figure 7-2. Efficiency vs Output Current

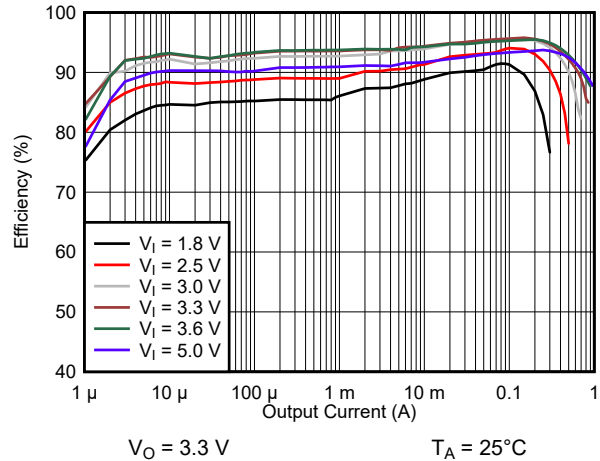


Figure 7-3. Efficiency vs Output Current

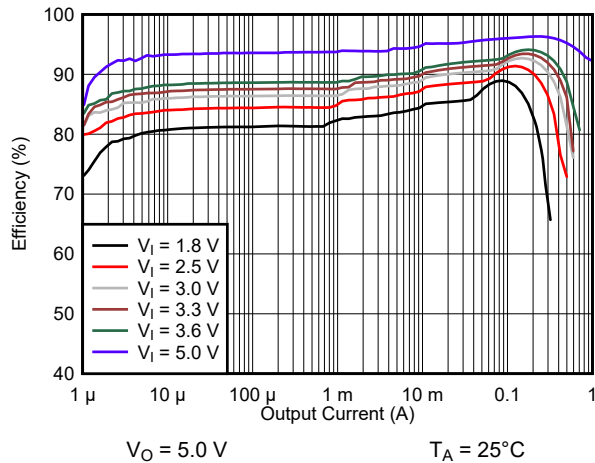


Figure 7-4. Efficiency vs Output Current

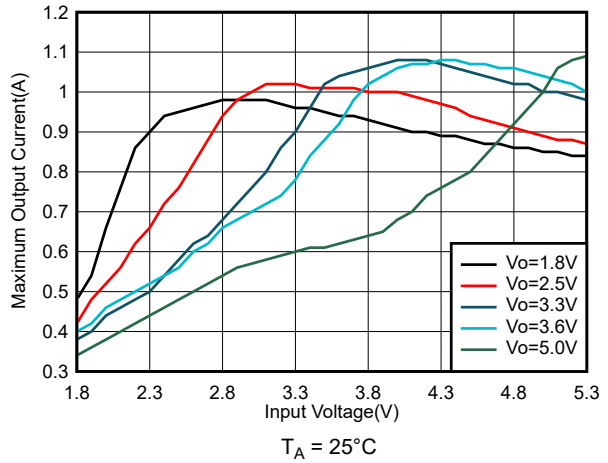


Figure 7-5. Typical Output Current Capability vs Input Voltage

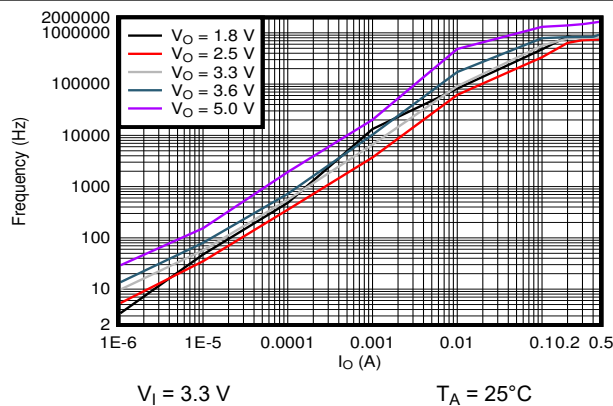


Figure 7-6. Typical Burst Switching Frequency vs Output Current

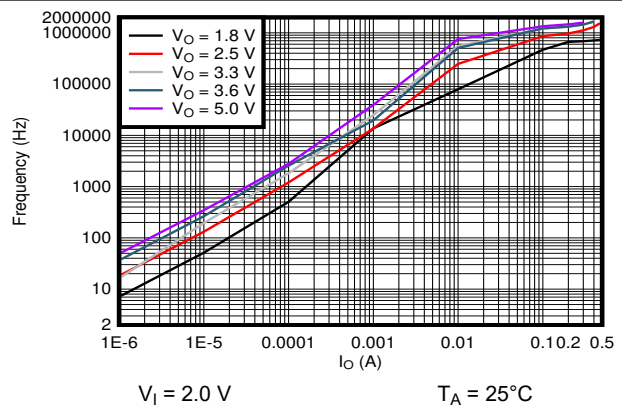


Figure 7-7. Typical Burst Switching Frequency vs Output Current

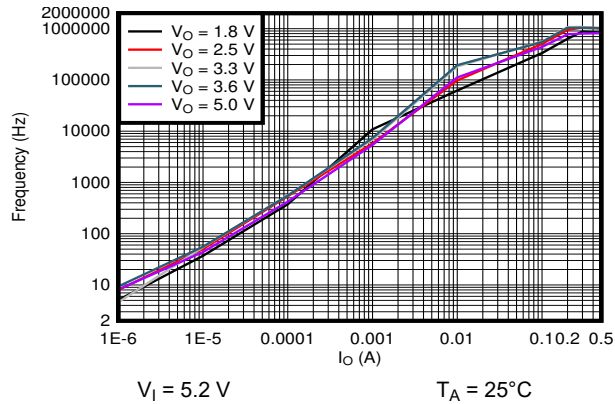


Figure 7-8. Typical Burst Switching Frequency vs Output Current

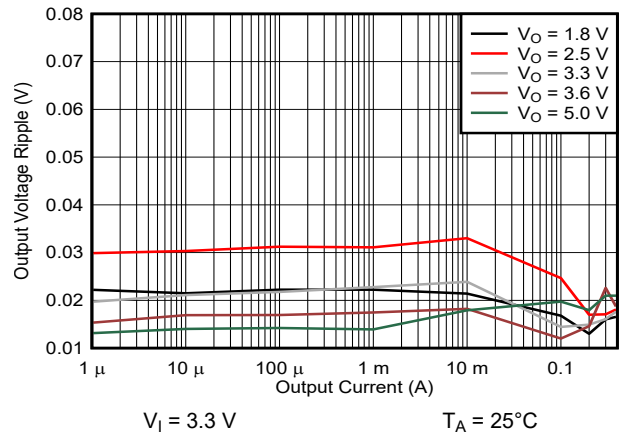


Figure 7-9. Output Voltage Ripple

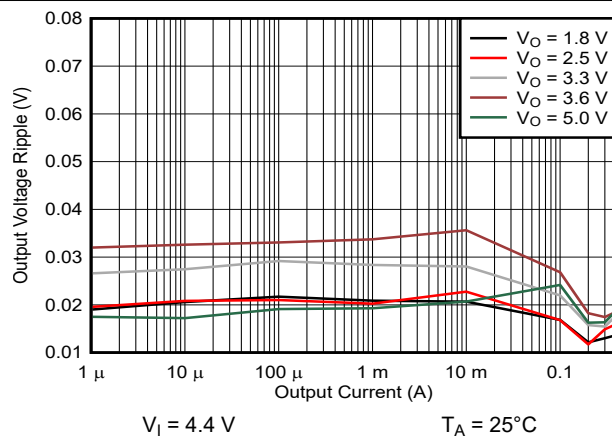


Figure 7-10. Output Voltage Ripple

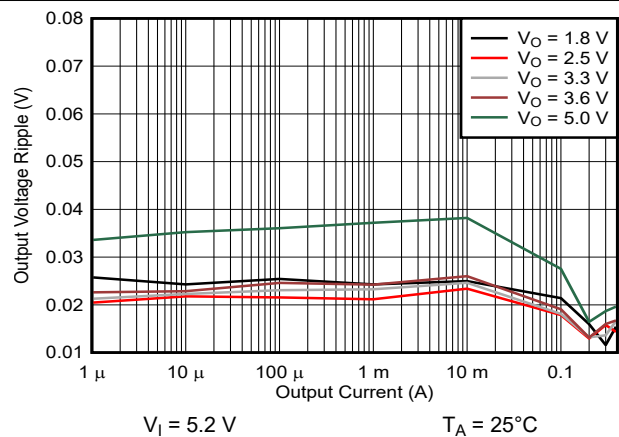


Figure 7-11. Output Voltage Ripple

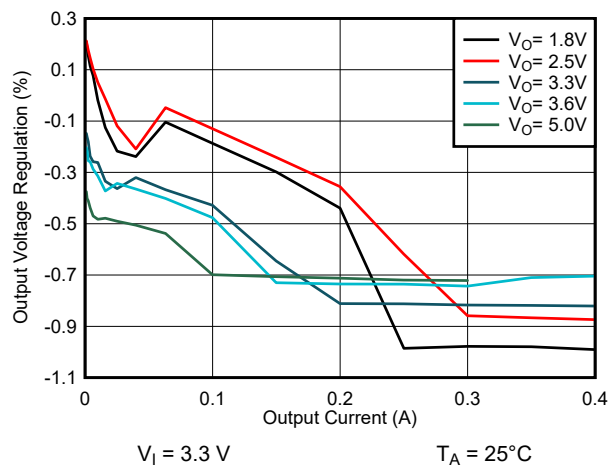


Figure 7-12. Load Regulation

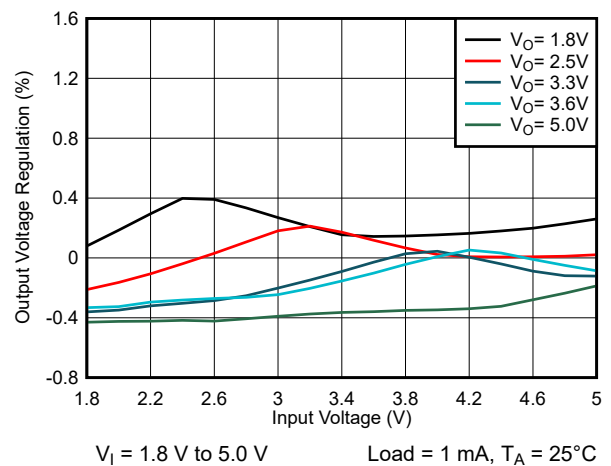
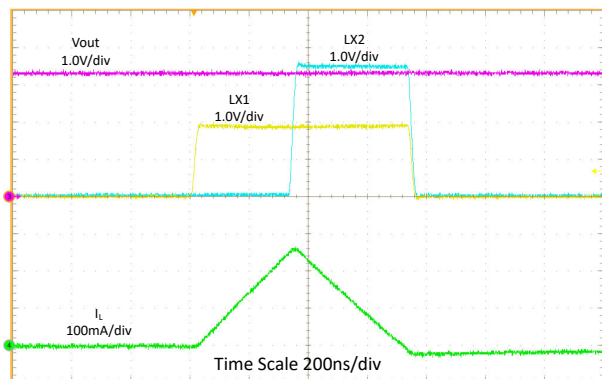


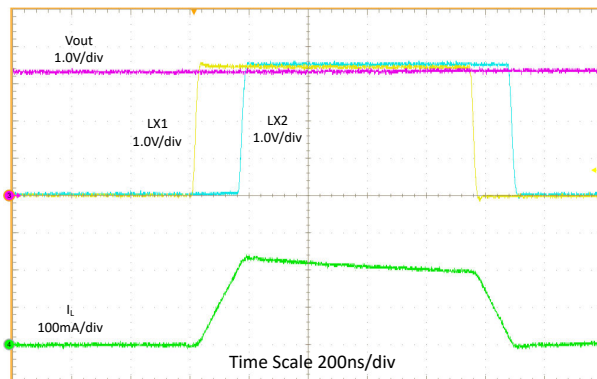
Figure 7-13. Line Regulation



$V_I = 1.8\text{ V}$, $V_O = 3.3\text{ V}$

No load

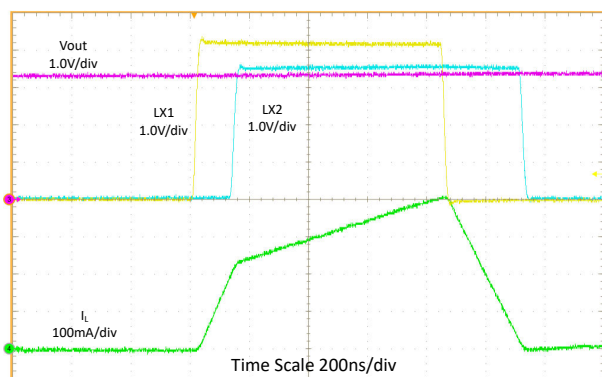
図 7-14. Switching Waveforms, Boost Operation



$V_I = 3.3\text{ V}$, $V_O = 3.3\text{ V}$

No load

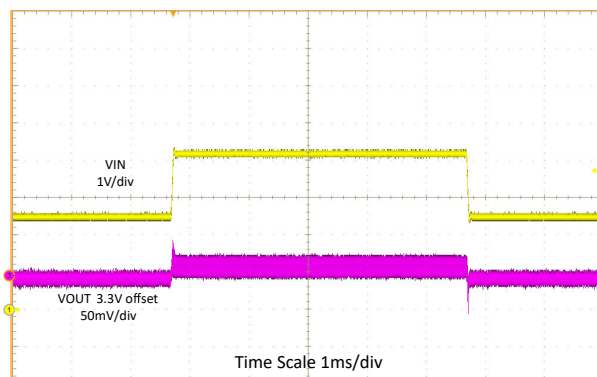
図 7-15. Switching Waveforms, Buck-Boost Operation



$V_I = 4.0\text{ V}$, $V_O = 3.3\text{ V}$

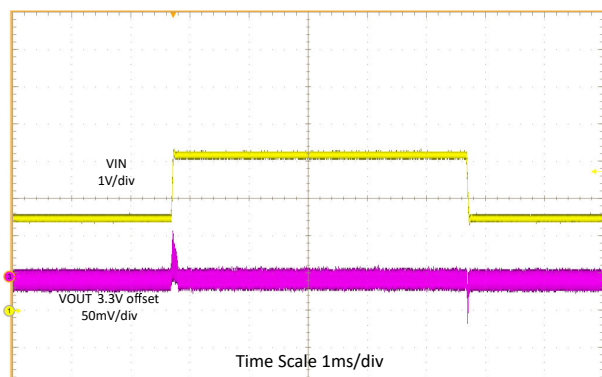
No load

図 7-16. Switching Waveforms, Buck Operation



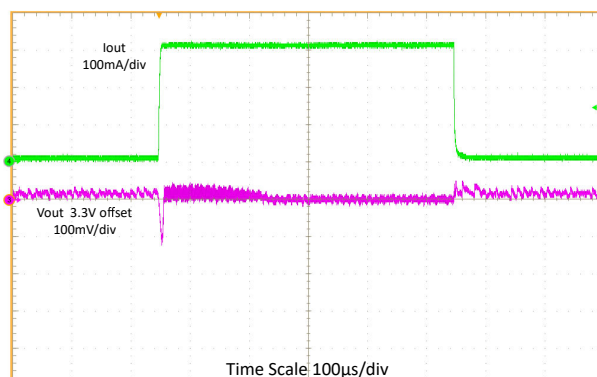
$V_I = 2.5\text{ V to } 4.2\text{ V}$, $V_O = 3.3\text{ V}$ Load = 200-mA resistive load

図 7-17. Line Transient, 200-mA Load



$V_I = 2.5\text{ V to } 4.2\text{ V}$, $V_O = 3.3\text{ V}$ Load = 400-mA resistive load

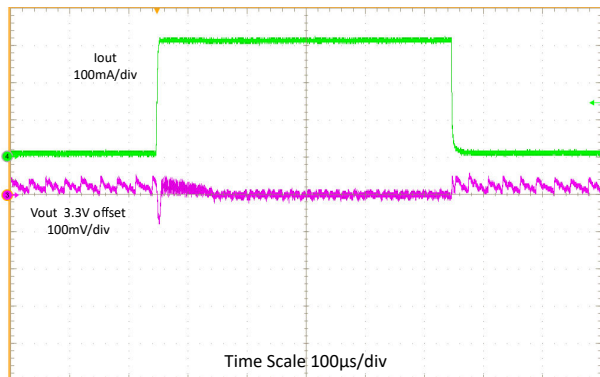
図 7-18. Line Transient, 400-mA Load



$V_I = 2.7\text{ V}$, $V_O = 3.3\text{ V}$

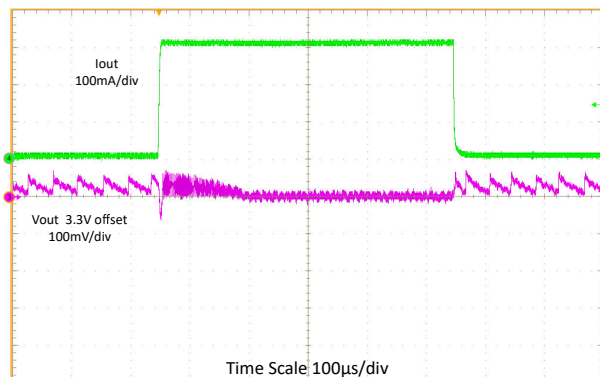
Load = 0 mA to 300 mA, $t_r/t_f = 2\text{ }\mu\text{s}$

図 7-19. Load Transient, 300-mA Step



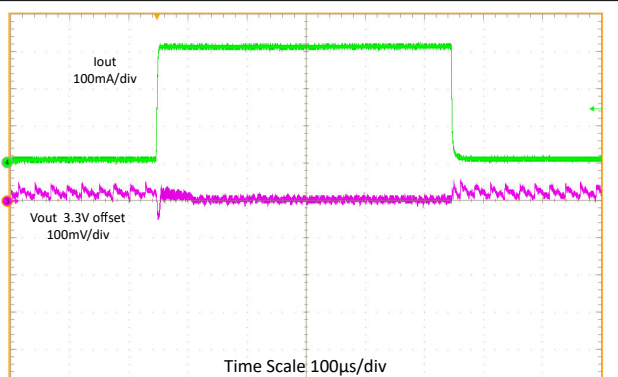
$V_I = 3.3\text{ V}$, $V_O = 3.3\text{ V}$ Load = 0 mA to 300 mA, $t_r/t_f = 2\text{ }\mu\text{s}$

図 7-20. Load Transient, 300-mA Step



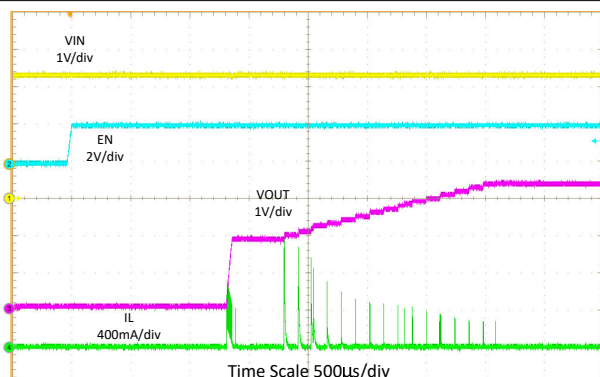
$V_I = 4.2\text{ V}$, $V_O = 3.3\text{ V}$ Load = 0 mA to 300 mA, $t_r/t_f = 2\text{ }\mu\text{s}$

図 7-21. Load Transient, 300-mA Step



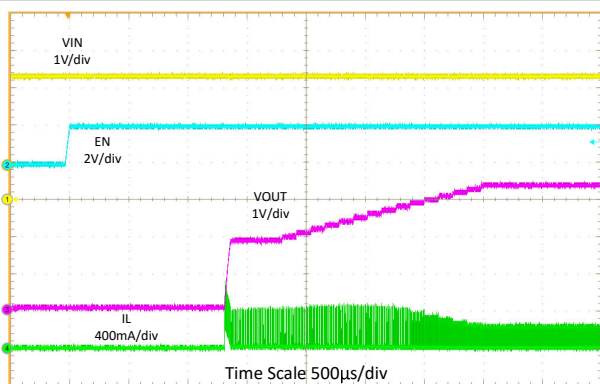
$V_I = 5.5\text{ V}$, $V_O = 3.3\text{ V}$ Load = 0 mA to 300 mA, $t_r/t_f = 2\text{ }\mu\text{s}$

図 7-22. Load Transient, 300-mA Step



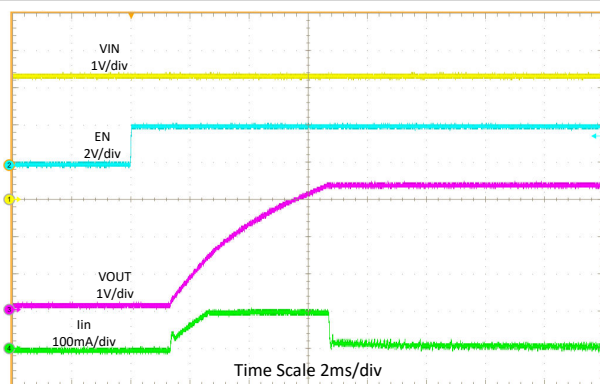
$V_I = 3.3\text{ V}$, $V_O = 3.3\text{ V}$ 10- μA resistive load

図 7-23. Start-Up Behavior from Rising Enable



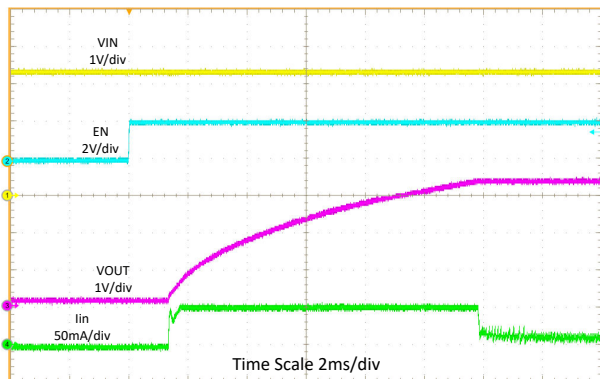
$V_I = 3.3\text{ V}$, $V_O = 3.3\text{ V}$ 100-mA resistive load

図 7-24. Start-Up Behavior from Rising Enable



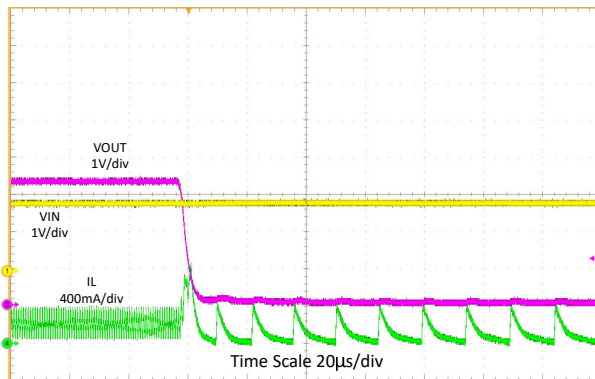
$V_I = 3.3\text{ V}$, $V_O = 3.3\text{ V}$ $C_1 = 32\text{ }\mu\text{F}$, $C_O = 300\text{ }\mu\text{F}$

図 7-25. Start-Up with 100-mA ICL



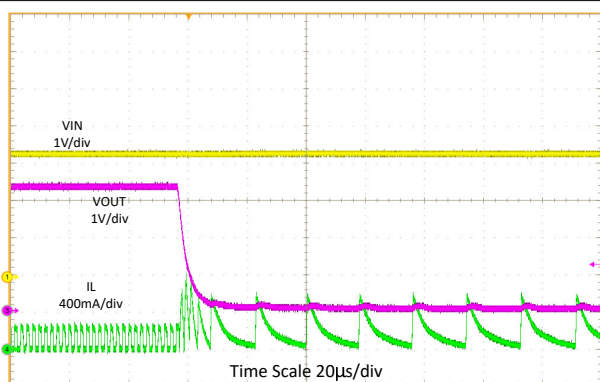
$V_I = 3.3\text{ V}$, $V_O = 3.3\text{ V}$ $C_I = 32\text{ }\mu\text{F}$, $C_O = 300\text{ }\mu\text{F}$

図 7-26. Start-Up with 50-mA ICL



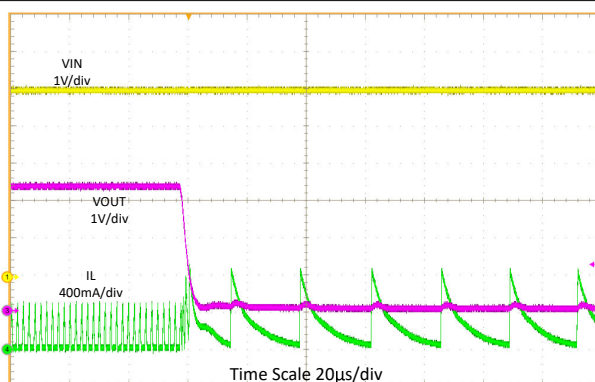
$V_I = 1.8\text{ V}$, $V_O = 3.3\text{ V}$ $T_A = 25^\circ\text{C}$

図 7-27. Short Circuit Behavior



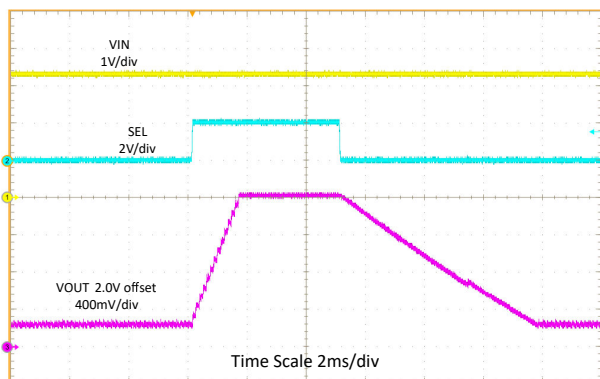
$V_I = 3.3\text{ V}$, $V_O = 3.3\text{ V}$ $T_A = 25^\circ\text{C}$

図 7-28. Short Circuit Behavior



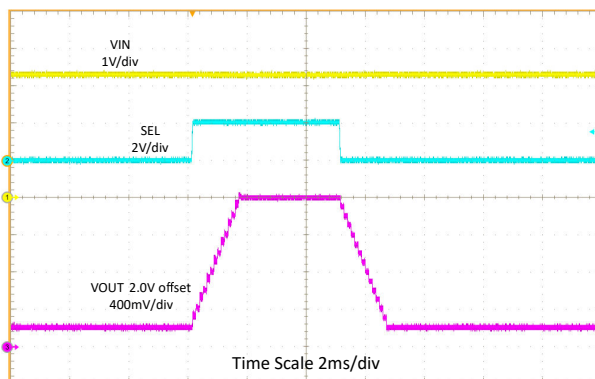
$V_I = 5.0\text{ V}$, $V_O = 3.3\text{ V}$ $T_A = 25^\circ\text{C}$

図 7-29. Short Circuit Behavior



$V_I = 3.3\text{ V}$, $V_{O(1)} = 2.2\text{ V}$, $V_{O(2)} = 3.6\text{ V}$ 0.1-mA resistive load

図 7-30. DVS Behavior at Light Load



$V_I = 3.3\text{ V}$, $V_{O(1)} = 2.2\text{ V}$, $V_{O(2)} = 3.6\text{ V}$ 400-mA resistive load

図 7-31. DVS Behavior at High Load

8 Power Supply Recommendations

The TPS63901 device is designed to operate with input supplies from 1.8 V to 5.5 V. The input supply must be stable and free of noise to achieve the full performance of the device. If the input supply is located more than a few centimeters away from the device, additional bulk capacitance can be required. The input capacitance shown in the application schematics in this data sheet is sufficient for typical applications.

9 Layout

9.1 Layout Guidelines

PCB layout is an important part of any switching power supply design. A poor layout can cause unstable operation, load regulation problems, increased ripple and noise, and EMI issues.

The following PCB layout design guidelines are recommended:

- Place the input and output capacitors close to the device.
- Minimize the area of the input loop, and use short, wide traces on the top layer to connect the input capacitor to the VIN and GND pins.
- Minimize the area of the output loop, and use short, wide traces on the top layer to connect the output capacitor to the VOUT and GND pins.
- The location of the inductor on the PCB is less important than the location of the input and output capacitors. Place the inductor after the input and output capacitors have been placed close to the device. Route the traces to the inductor on an inner layer if necessary.

9.2 Layout Example

Figure 9-1 shows an example of a PCB layout that follows the recommendations of the previous section.

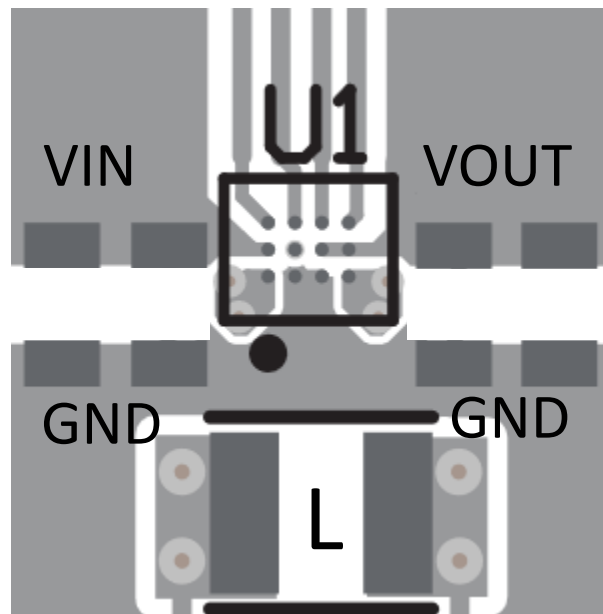


Figure 9-1. PCB Layout Example

10 Device and Documentation Support

10.1 Device Support

10.1.1 Third-Party Products Disclaimer

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10.2 Documentation Support

10.2.1 Related Documentation

For related documentation see the following:

Texas Instruments, [TPS63901 EVM User Guide](#)

10.3 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

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10.7 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

11 Revision History

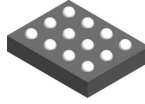
資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision A (June 2022) to Revision B (August 2024)	Page
• Added YCJ0012-C02 packaging information.....	29

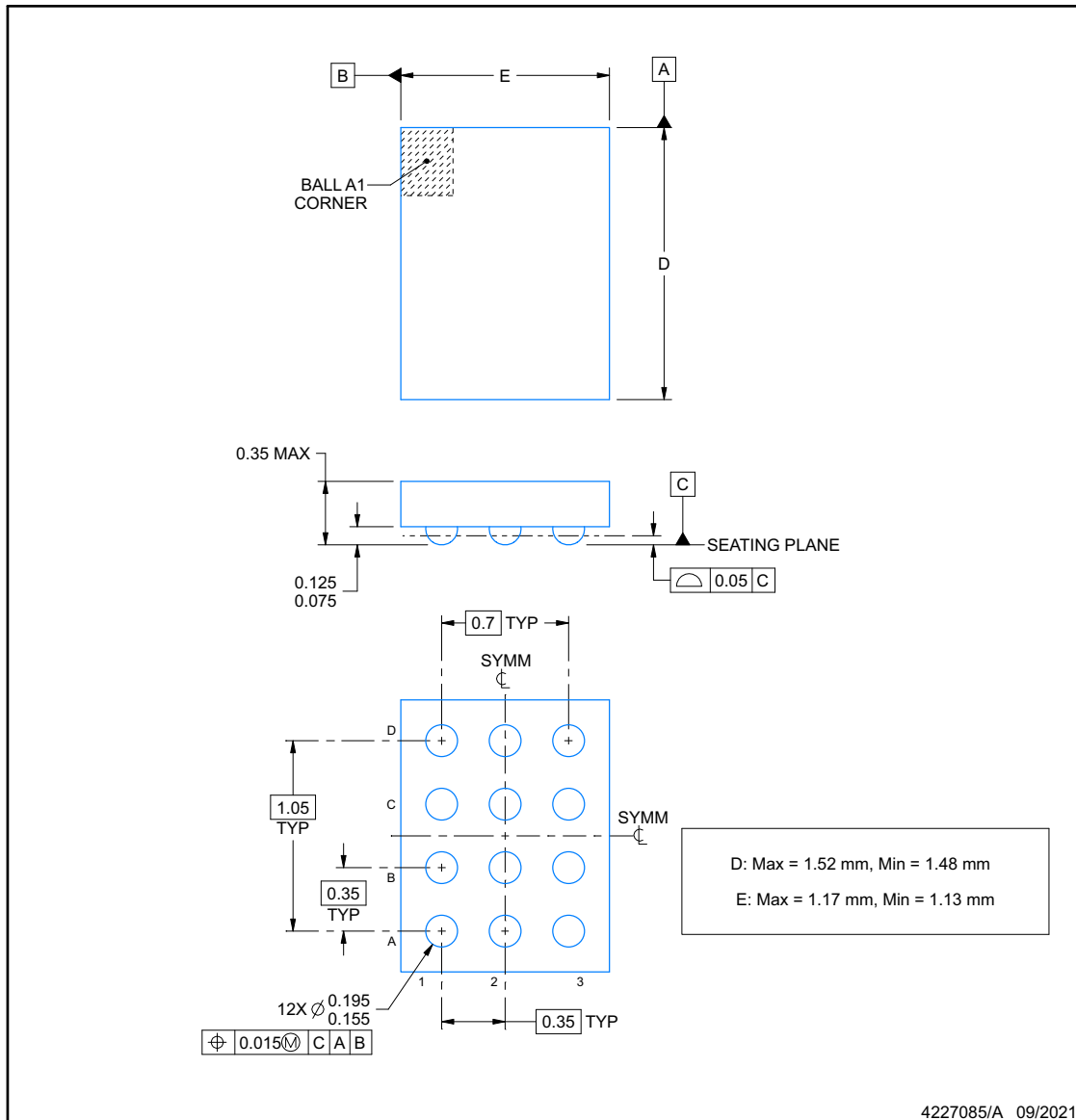
Changes from Revision * (December 2021) to Revision A (June 2022)	Page
• ドキュメントのステータスを「事前情報」から「量産データ」に変更.....	1

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**YCJ0012-C02****PACKAGE OUTLINE****DSBGA - 0.35 mm max height**

DIE SIZE BALL GRID ARRAY

**NOTES:**

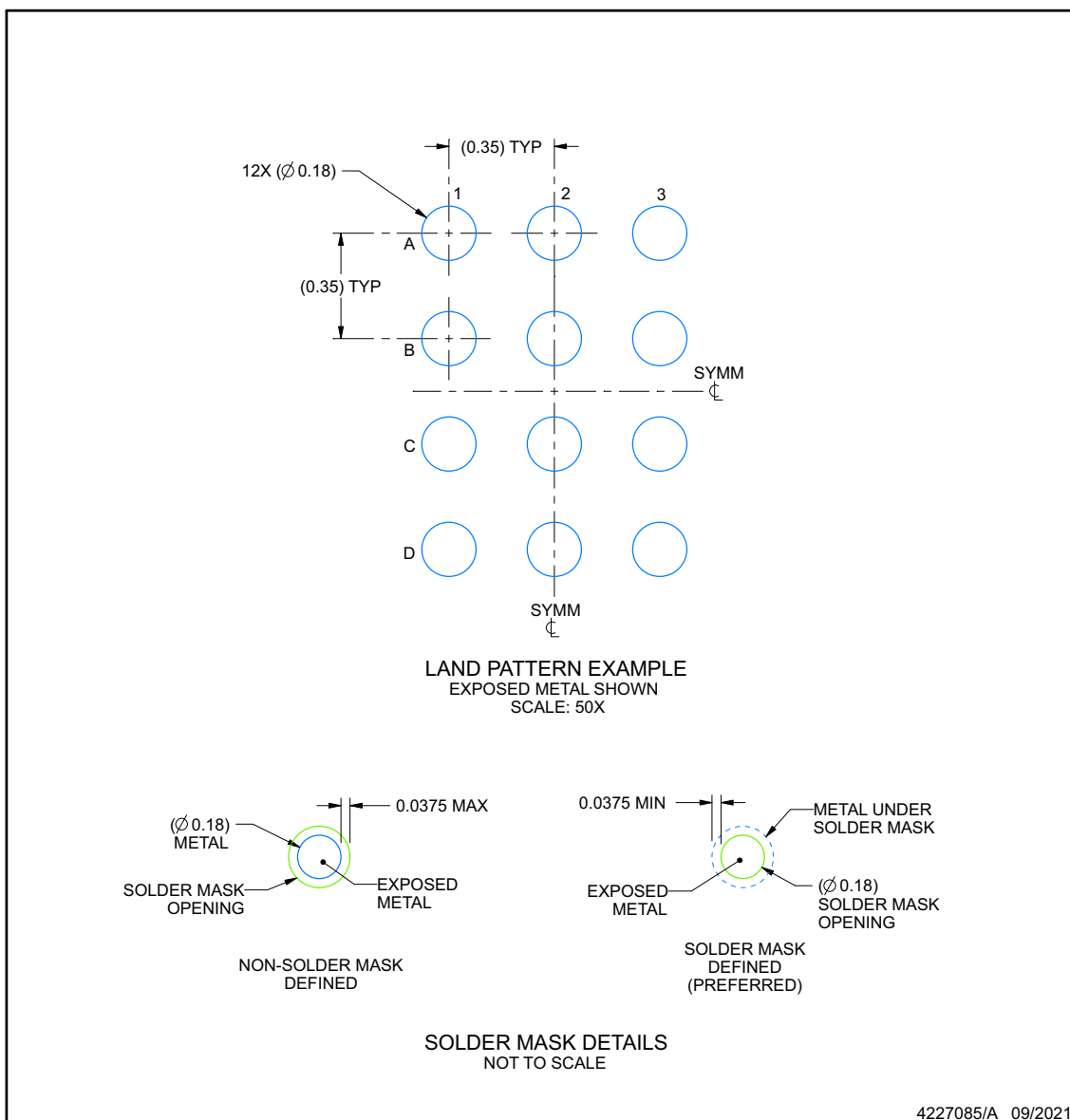
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

YCJ0012-C02

DSBGA - 0.35 mm max height

DIE SIZE BALL GRID ARRAY

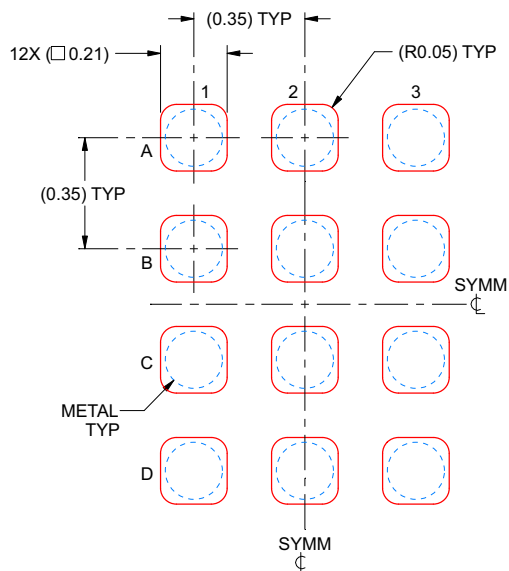


NOTES: (continued)

- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN**YCJ0012-C02****DSBGA - 0.35 mm max height**

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
 BASED ON 0.075 mm THICK STENCIL
 SCALE: 50X

4227085/A 09/2021

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS63901YCJR	Active	Production	DSBGA (YCJ) 12	3000 LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	3901
TPS63901YCJR.A	Active	Production	DSBGA (YCJ) 12	3000 LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	3901

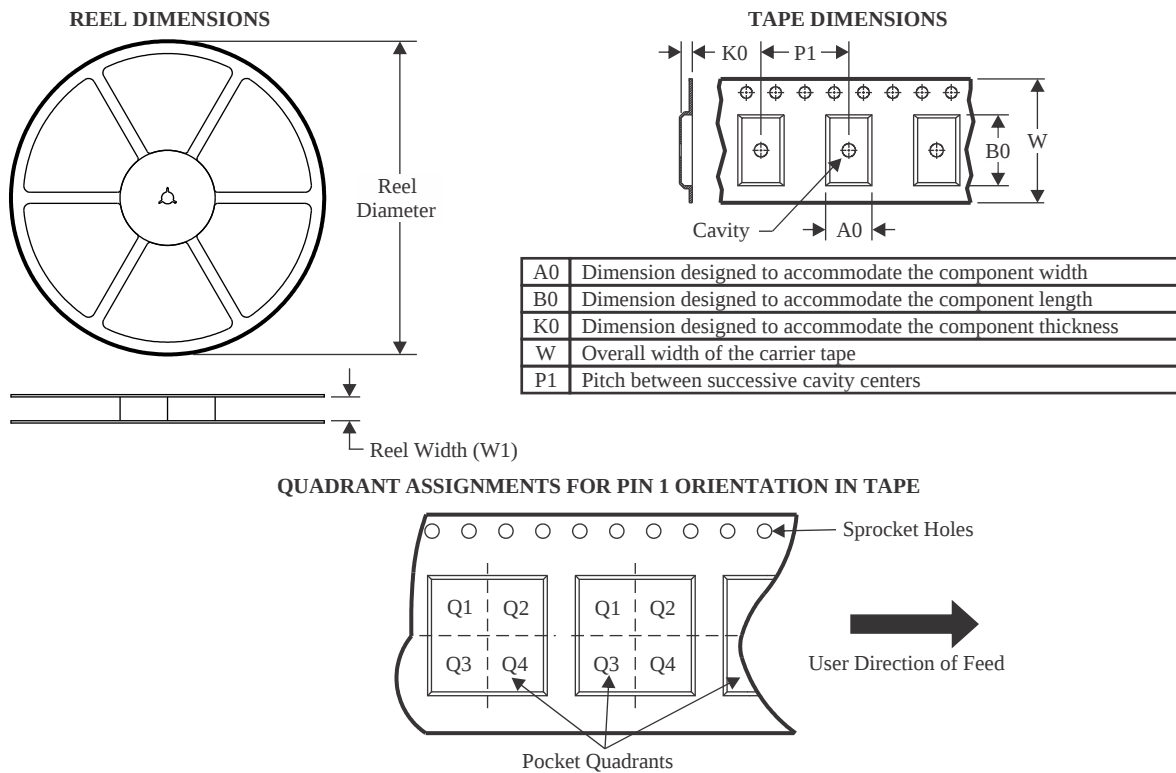
- ⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).
- ⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- ⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- ⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- ⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- ⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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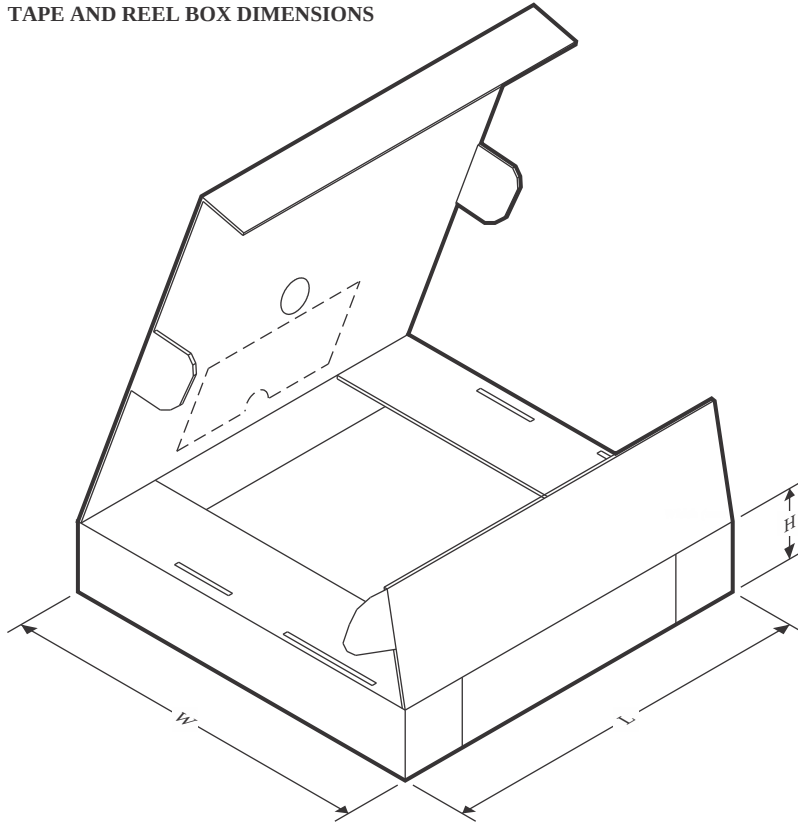
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS63901YCJR	DSBGA	YCJ	12	3000	180.0	8.4	1.26	1.65	0.43	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS63901YCJR	DSBGA	YCJ	12	3000	182.0	182.0	20.0



1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

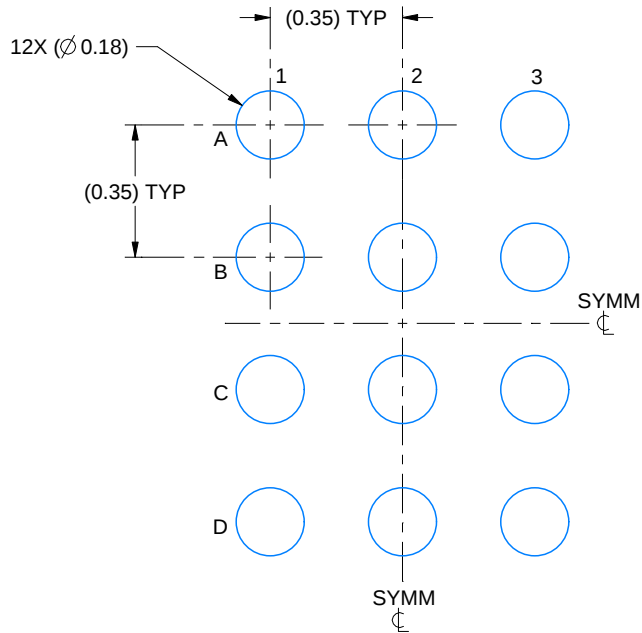
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

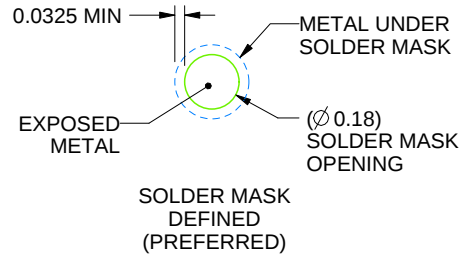
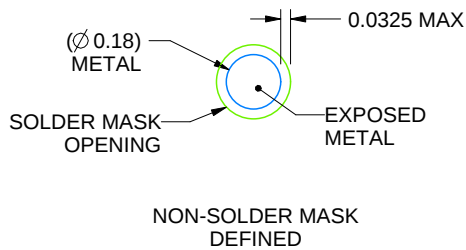
YCJ0012

DSBGA - 0.35 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 50X

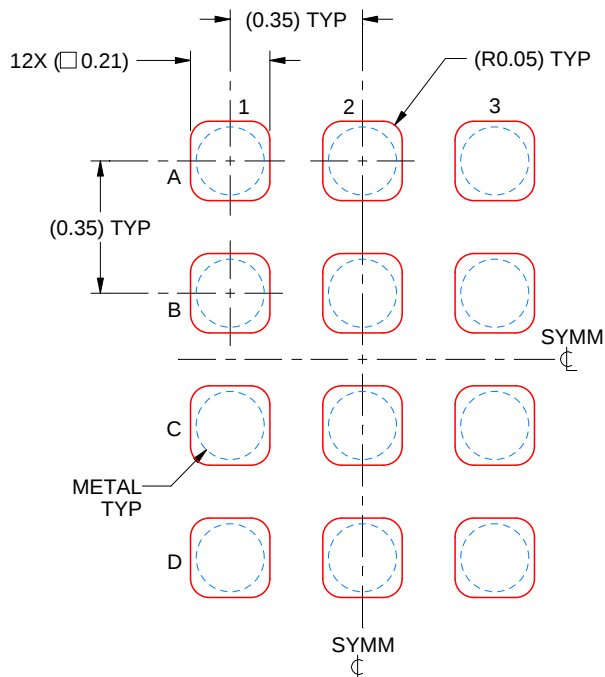


SOLDER MASK DETAILS
NOT TO SCALE

4224964/A 04/2019

NOTES: (continued)

- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).



SOLDER PASTE EXAMPLE
 BASED ON 0.075 mm THICK STENCIL
 SCALE: 50X

4224964/A 04/2019

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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